



PRODUCT SPECIFICATION

5.0 PERFORMANCE

5.1 ELECTRICAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
1	Capacitance	Measure between adjacent terminals	1.2 pf max
2	Insulation Resistance	Test between adjacent contact at 500 V DC for 1 minute, per (MIL-STD-1344 MTD 3001.1)	1000 Megaohms minimum
3	Dielectric Strength	Test between adjacent contact at 500VAC rms and 1 minute hold time.	No breakdown

5.2 MECHANICAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
4	Pin Retention Force in Housing	Push pin axially from housing at a rate of 12.7mm/min (0.50 inch/min)	0.85 Kgf min

REVISION: B7	ECR/ECN INFORMATION: EC No: S2011-1026 DATE: 2011/06/06	TITLE: 2MM DUAL ROW OR SINGLE ROW (SMT/ VERTICAL/ RIGHT ANGLE) HEADER	SHEET No. 2 of 4
DOCUMENT NUMBER: PS-87761-100	CREATED / REVISED BY: SKANG 2011/06/06	CHECKED BY: ATSEE 2011/06/21	APPROVED BY: MLONG 2011/06/21



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5.3 ENVIRONMENTAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
5	Temperature Rise	Apply 2 amps DC to the header and measure contact temperature rise for 48 hours	30°C maximum temperature rise above ambient.
6	Solderability	Solder Time: 5 ± 0.5 sec. Solder Temperature: 245 ± 5 °C	Soldertail should have 95% continuous new solder coating coverage (Apply to non-kinked Soldertail only)
7	Resistance to Soldering Heat (Wave Soldering) For Series a)87760 b)87758, 87830, 87761 c) Other series	Sample mounted on PCB and subject to wave soldering, a)Temperature : 260 ± 5 °C for 12 ± 2 Sec b)Temperature : 260 ± 5 °C for 10+2/-0Sec c) Temperature : 245 ± 5 °C for 5Sec	Appearance : No Damage
8	Resistance to Solder Heat (Reflow) For SMT Series 87753, 87756, 87759, 87762, 87763, 87858, 87979, 87830	Pass Jack through IR machine for 3 cycles of the following reflow profile: Average Ramp Rate 3°C/sec max. Preheat Temp. (Min.) 150°C Preheat Temp. (Max.) 200°C Preheat Time 60 – 180 sec Ramp to Peak 3°C/sec max. Time over liquidus (217°C) 60 – 150 sec Peak Temperature 260 +0/-5°C Time within 5°C of peak 20 – 40 sec. Ramp – Cool Down 6°C/sec max. Time 25°C to Peak 8 mins max.	Appearance : No Damage

6.0 Packaging

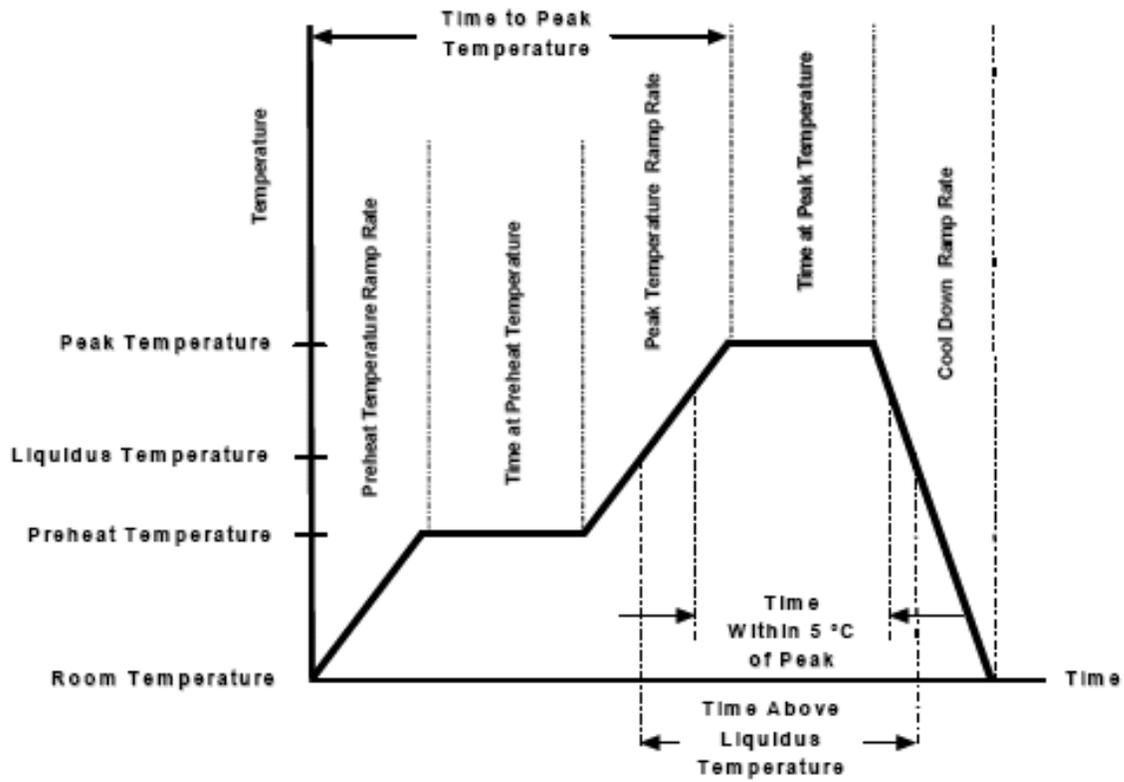
Product shall be packaged and protected against damage during handling, transportation and storage.

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7.0 SURFACE MOUNT REFLOW TEMPERATURE PROFILE



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